

203	9	"L2020" and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:46
204	1440	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (leads or lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:46
205	1131	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:47
206	45	((leadframe or (lead adj frame)) and (electrodeposition or bath)) and (leads or lead)) and (@ad<20010418)) and leadless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:47
	370	electrodeposition same frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 18:31
	309	(electrodeposition same frame) and (@ad<20010418)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:25
	97	((electrodeposition same frame) and (@ad<20010418)) and (chip or die or ic or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/15 21:24